

Serial No. : 2018-0053

DATE: 2018/01/22

Shanghai Winson Electronics Co.,LTD

ITEM:	CRYSTAL OSCILLATOR
TYPE :	DSA535SG
NOMINAL FREQUENCY :	40.000MHz
SPEC No. :	1XTQ4000EGA

If there is a change in this specifications, the specification number may be changed.

	RECEIPT
DATE	
RECEIVED	(signature)
	(name)

General Manufacturer of Quartz Devices

1389 Shinzaike, Hiraoka-cho, Kakogawa, Hyogo 675-0194 Japan Phone (81)79-425-3141 Fax (81)79-425-1134 http://www.kds.info/index_en.htm

74. Takase.

C.ENG.

E. Kameda ENG.

Device Name
 Model Name
 Nominal Frequency
 Weight
 VC-TCXO
 DSA535SG
 40.000 MHz
 0.08g max.

5. Absolute Maximum Value

	Item	Symbol	Rating	unit
1	Supply Voltage	V _{CC}	-0.3 ~ +6.0	V
2	Storage Temperature Range	T_ _{STG}	-40 ~ +85	°C

6. Recommended Operating Conditions

	Item	Symbol	min.	typ.	max.	unit
1	Supply Voltage	V _{CC}	+3.135	+3.3	+3.465	V
2	Frequency Control Voltage Range	V _{CONT}	+0.5	+1.5	+2.5	V
3	Output Enable					
	1. "L" level	V_{IL}	_	_	V _{CC} x0.3	V
	2. "H" level	V _{IH}	V _{CC} x0.7	_	_	V
4	Operable Temperature Range	T_ _{OPR}	-40	_	+85	°C
5	Load impedance (resistance part)	L_cmos	_	15	_	pF

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7. Electrical Characteristics

(T_A =-40 \sim +85 $^{\circ}$ C, L_CMOS =15pF, V_{CC=}+3.3V, V_{CONT=}+1.5Vunless otherwise noted)

$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		14	Canditiana		Limits		14	Natas
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		Item	Conditions	min.	typ.	max.	unit	Notes
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	1	Current consumption		_	_	+5.0	mA	
2. Fall Time	2	Output						1
3. Low Level V _{CC} x0.1 V 4. High Level V _{CC} x0.9 V 5. Symmetry V _{CC} x0.5 Level 40/60 50 60/40 % 1. Tolerance After 2 times reflow (TA = +25 °C) - ±1.50 ppm 2.		1. Rise Time	V _{CC} x0.1 ~ V _{CC} x0.9	_	_	7	ns	
		2. Fall Time	V _{CC} x0.9 ~ V _{CC} x0.1	_	_	7	ns	
5. Symmetry V _{CC} x0.5 Level 40/60 50 60/40 % 3 Frequency Stability 1. Tolerance After 2 times reflow (T _A = +25 °C) - - ±1.50 ppm 2.		3. Low Level		_	-	V _{CC} x0.1	V	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		4. High Level		V _{CC} x0.9	-	_	V	
		5. Symmetry	V _{CC} x0.5 Level	40/60	50	60/40	%	
	3	Frequency Stability						
		1.Tolerance	After 2 times reflow (T _A = +25 °C)	_	_	±1.50	ppm	2,3
		2.vs Temperature	T _A =-40 ~ +85 °C	_	_	±0.28	ppm	4
		3.vs Supply Voltage	Vcc = +3.3V ±5%	_	-	±0.20	ppm	
4 Start Up Time @90% of Final Vour level		4.vs Load Variation	L_CMOS = 15pF ±5%	_	-	±0.20	ppm	
		5.vs Aging	T _A = Room ambient	_	-	±1.00	ppm/year	
	4	Start Up Time	@90% of Final Vout level	_	-	2.0	ms	
			Within ±0.1ppm of final frequency	_	-	3.0	ms	
2.Input Resistance 100 – kΩ	5	Frequency Control						
		1.Control Range	VCONT=+1.5V ± 1.0V	±5.0	_	_	ppm	5
6 SSB Phase Noise Relative to F0 Level Offset 100Hz103 dBc/Hz		2.Input Resistance		100	-	_	kΩ	
TOURING TOURS TOURS TOURS TOURS	6	SSB Phase Noise	Relative to F0 Level Offset 100Hz	-	-	-103	dBc/Hz	
Relative to F0 Level Offset 1kHz128 dBc/Hz			Relative to F0 Level Offset 1kHz	-	_	-128	dBc/Hz	
Relative to F0 Level Offset 10kHz145 dBc/Hz			Relative to F0 Level Offset 10kHz	_	_	-145	dBc/Hz	1

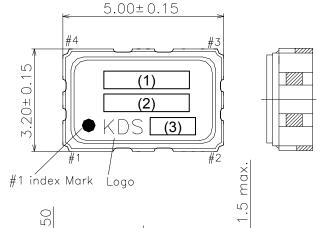
Notes

- 1. CMOS Output
- 2. Ref. to Nominal Frequency.
- 3. Please leave after Reflow in 2H or more at room ambient.
- 4. Ref. to Frequency (Ta=+25 °C)
- 5. Positive slope (Frequency becomes high in proportion to frequency control voltage.)

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8. Outline, Pin Connections

C



Pin Connections

Pin No.	Connection
#1	V _{CONT}
#2	GND
#3	OUTPUT
#4	V _{CC}

Marking

(1) Frequency 40000 (kHz, 5digits)

"A535SG" (2) Model code

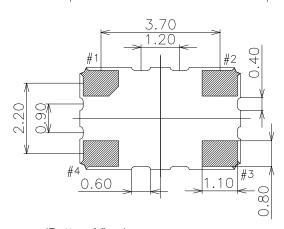
(3) Date code Year (1digit) + Week (2digits)

e.g. 2018/1/1 -> 801



Dimensional Tolerance:+/-0.15 (Unless otherwise noted)

Spec. No.



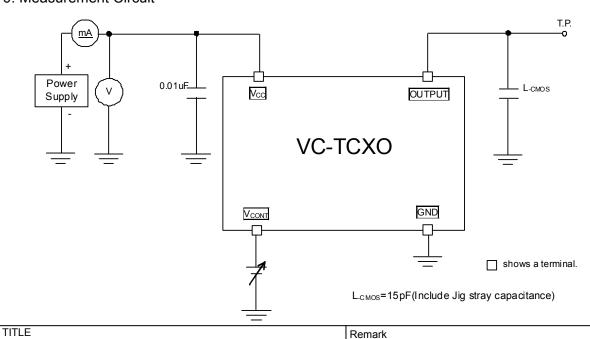
(Bottom View)

9. Measurement Circuit

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10. Mechanical Characteristics

All test is performed after 3times reflow (Clause.13) except 10.10 (Resistance to soldering heat)

	Item	I test is performed after 3times reflow (Clause.13) except 1	`
1		Description (On a graph)	Requirements
1	Drop	Natural drop (On concrete)	
		Mounting on the set or test fixture.(Total weight 100g)	
		Height: 150cm	df/f=<±1.0ppm
		Direction: X,Y,Z, 6directions	
		Test cycle : 3cycles	
	\ r \ \ c	Reference specification : EIAJ-ED-4702A Method5	
2	Vibration	Sweep range: 10~500Hz	
		Sweep speed: 11min/cycle	
		Amplitude : 1.5mm (10~55Hz)	1515
		Acceleration: 200m/s ² (55~500Hz)	df/f=<±0.5ppm
		Direction: X,Y,Z, 3directions	
		Test cycle: 10cycles	
	0	Reference specification : IEC 60068-2-6	
3	Shock	Acceleration: 1000m/s ²	
		Direction : X,Y,Z, 6directions	
		Duration : 6ms	df/f=<±0.5ppm
		Test cycle: 3cycles/each directions	
		Reference specification : IEC 60068-2-27	
4	PCB bend	PWB: t=1.6mm	
	strength	Pressure speed : 1.0mm/s	df/f=<±0.5ppm
		Bend width : 1→2→3mm	No visible damage.
		Duration : 10±1s	No leak damage.
		Reference specification : IEC 60068-2-21 Ue1	
5	Adherence nature	PWB : t=1.6mm	
		Direction : X,Y, 2directions	df/f=<±0.5ppm
		Pressure : 10N	No visible damage.
		Duration: 10±1s	No leak damage.
		Reference specification : IEC 60068-2-21 Ue3	
6	Package strength	Pressure : 10N	df/f=<±0.5ppm
		Duration : 10±1s	No mechanical damage.
		Reference specification : IEC 60068-2-77	No leak damage.
7	Gross leak	It is immersed for 3min into +125±5°C	
		Chlorofluorocarbon (CFCs) liquid.	No continuous air bubbles.
		Reference specification : IEC 60068-2-17	
8	Fine leak	It shall be measured by the helium leak detector	
		after pressurization for 60min by the pressure	Less than 1.0x10 ⁻⁹ Pa m ³ /s.
		of (3.92±0.49) x10 ⁵ Pa in a helium gas atmosphere.	2000 than 1.0x10 1 a 11170.
		Reference specification : IEC 60068-2-17	
9	Solderability	Solder bath temperature : +245±5°C	A new uniform coating of solder
		Duration: 3±0.3s	shall cover a minimum of 95%
		Reference specification : IEC 60068-2-58	of the surface being immersed.
10	Resistance to	1) Solder iron method	
	soldering heat	Bit size : B(φ3) Bit temperature : +350±10°C	df/f=<±0.5ppm
		Duration : 3+1/-0s /each terminal	$dV_{OUT} = < \pm 0.2V_{P-P}$
		It shall be measured after 2h at room temperature,	No visible damage.
		humidity. Reference specification : IEC 60068-2-20	
		2) Reflow	
		In refer to temperature profile shown in clause13.	df/f=<±1.0ppm
		Test cycle : 3cycles	$dV_{OUT} = < \pm 0.2V_{P-P}$
		It shall be measured after 2h at room temperature,	No visible damage.
		humidity. Reference specification : IEC 60068-2-58	

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11. Environmental Characteristics

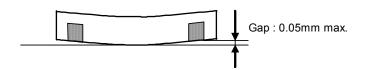
All test is performed after 3times reflow (Clause13)

	Item	Description	Requirements
1	Low temperature	Temperature : -40±3°C	df/f=<±1.0ppm
	storage	Duration: 1000h	$dV_{OUT} = < \pm 0.2V_{P-P}$
		It shall be measured after 2h at room temperature,	The electrical characteristics
		humidity. Reference specification : IEC 60068-2-1 Ab	are satisfied.
2	High temperature	Temperature : +85±2°C	df/f=<±1.0ppm
	storage	Duration: 1000h	$dV_{OUT} = <\pm 0.2V_{P-P}$
		It shall be measured after 2h at room temperature,	The electrical characteristics
		humidity. Reference specification : IEC 60068-2-2 Bb	are satisfied.
3	Humidity	Temperature : +85±2°C	df/f=<±1.0ppm
		R.H. 85±5%	$dV_{OUT} = < \pm 0.2V_{P-P}$
		Duration: 1000h	The electrical characteristics
		It shall be measured after 2h at room temperature,	are satisfied.
		humidity. Reference specification : IEC 60068-2-78	are satisfied.
4	HTB	Temperature : +85±2°C	df/f=<±1.0ppm
		Duration: 1000h	dV _{OUT} =<±0.2V _{P-P}
		BIAS : Max value of supply voltage	The electrical characteristics
		It shall be measured after 2h at room temperature,	are satisfied.
		humidity. Reference specification : IEC 60068-2-2 Bb	are satisfied.
5	THB	Temperature : +40±2°C	
		R.H. 90~95%	df/f=<±1.0ppm
		Duration: 1000h	$dV_{OUT} = < \pm 0.2V_{P-P}$
		BIAS : Max value of supply voltage	The electrical characteristics
		It shall be measured after 2h at room temperature,	are satisfied.
		humidity. Reference specification : IEC 60068-2-78	
6	Thermal shock	Thermal shock : -40±3°C : 0.5h ⇔ +85±2°C : 0.5h	df/f=<±1.0ppm
		Test cycle : 200cycles	dV _{OUT} =<±0.2V _{P-P}
		Shift time : 2~3min	The electrical characteristics
		It shall be measured after 2h at room temperature,	are satisfied.
		humidity. Reference specification : IEC 60068-2-14	are satisfied.
7	ESD	Model : Machine Model (MM)	
		V=±200V (C=200pF, R=0Ω)	df/f=<±1.0ppm
		Number of times : 3times	$dV_{OUT} = < \pm 0.2V_{P-P}$
		Each terminal except common terminal.	The electrical characteristics
		(Connect to test terminal)	are satisfied.
		Reference specification : EIA/JESD22-A115	
		Model : Human Body Model (HBM)	
		V=±1500V (C=100pF, R=1500Ω)	df/f=<±1.0ppm
		Number of times : 3times	$dV_{OUT} = < \pm 0.2V_{P-P}$
		Each terminal except common terminal.	The electrical characteristics
		(Connect to test terminal)	are satisfied.
		Reference specification : EIA/JESD22-A114	

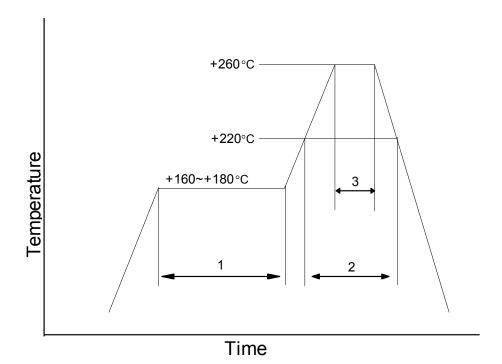
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12. Flatness of Terminal

When the component is placed on the flat surface, the gap from the connecting terminal shall not exceed 0.05 mm.



13. Reflow Profile



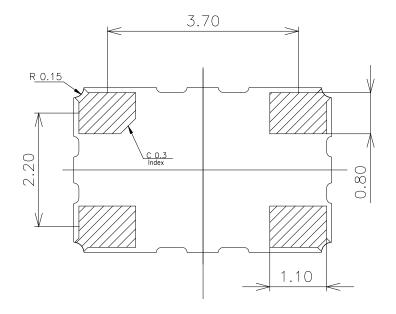
1	Preheat	+160~+180°C	120s
2	Primary Heat	+220°C	60s
3	Peak	+260°C	10s max.

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14. Terminals / Land Pattern Layout / Metal Mask Hole

14.1 Terminals

A through hole is not located on the bottom (mounting side).



unit: mm

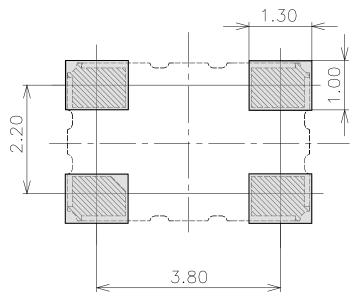
Dimensional Tolerance: ±0.15mm



Mounting terminal

14.2 Land Pattern Layout / Metal Mask Hole

The following land pattern is reference design. The electrical characteristic shall be satisfied with mounting to this land. The land pattern can be changed in the limits to which a test land and a mounting land are not connected. And it does not any effect to the electrical characteristics. Mask thickness recommends 0.12mm.



TOP VIEW

unit: mm

Dimensional Tolerance: ±0.15mm

——— Land Pattern

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15. Packing Condition

15.1 Taping package

(1) Emboss tape format and dimensions

See Fig.1

(2) Quantity on reel

4000pcs. max. / reel

(3) Taping specification

See Fig.2

No lack of a product.

(4) Reel specification

See Fig.3

(5) Taping material list

See right table.

15.2 Packing

The products packed in the antistatic bag.

*Moisture sensitivity level: IPC/JEDEC Standard J-STD-033 / Level 1

No dry pack required and baking after re-storage is unnecessary.

15.3 Packing box

Max 5 reels/packing box. However, in the case of less than 5 reels, It is contained by any boxes.

The space in a box is fill up with a cushion.

15.4 Label detail

A Lot label and bar code label are put on a reel. A shipping label and Barcode Label are put on a packing box.

Lot label

TYPE	(Model Name)
SPEC NO.	(Spec. Number)
PARTS NO.	(User's Parts Number)
LOT NO.	(Lot Number)
FREQ.	(Nominal Frequency)
Q'TY	(Quantity)
l KDS	DAISHINKU CORP

Shipping label

Taping material List

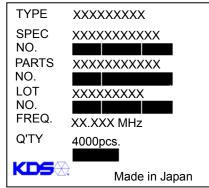
Emboss: PS (Conductivity)

Reel: PS (Conductivity)

ITEM	(Model Name)
SPEC	(Spec. Number)
DELIVERY DATE	(Delivery Date)
Q'TY	(Quantity)
NOTES	(User's Parts Number)
DAISHINKU CORP.	

Cover Tape: PET + Olefin Resin (Conductivity)

Lot label (Example)



Formation of a lot number

e.g. AH8101001

A H 8101 001

Manufacturing site code Product code year/ month/ day Serial No.

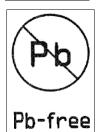
The notation method of a manufacture year, month, and day. (4digits alphanumeric character)

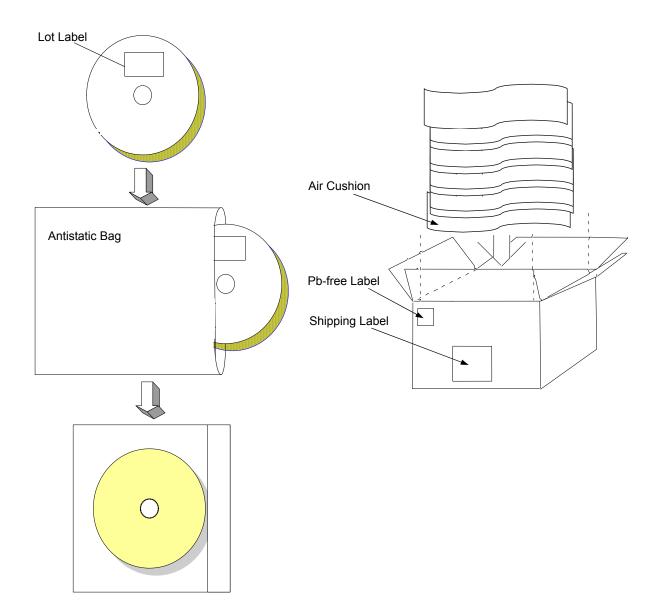
YMDD (4digits) e.g.) 2018 /01 /01→ 8101
 Year 1digit (Last digit of Year)
 Month 1digit alphanumeric symbol
 DD Day 2digits numerical characters of day

Month	Jan.	Feb.	Mar.	Apr.	May.	Jun.	Jul.	Aug.	Sep.	Oct.	Nov.	Dec.
Symbol	1	2	3	4	5	6	7	8	g	0	N	ח

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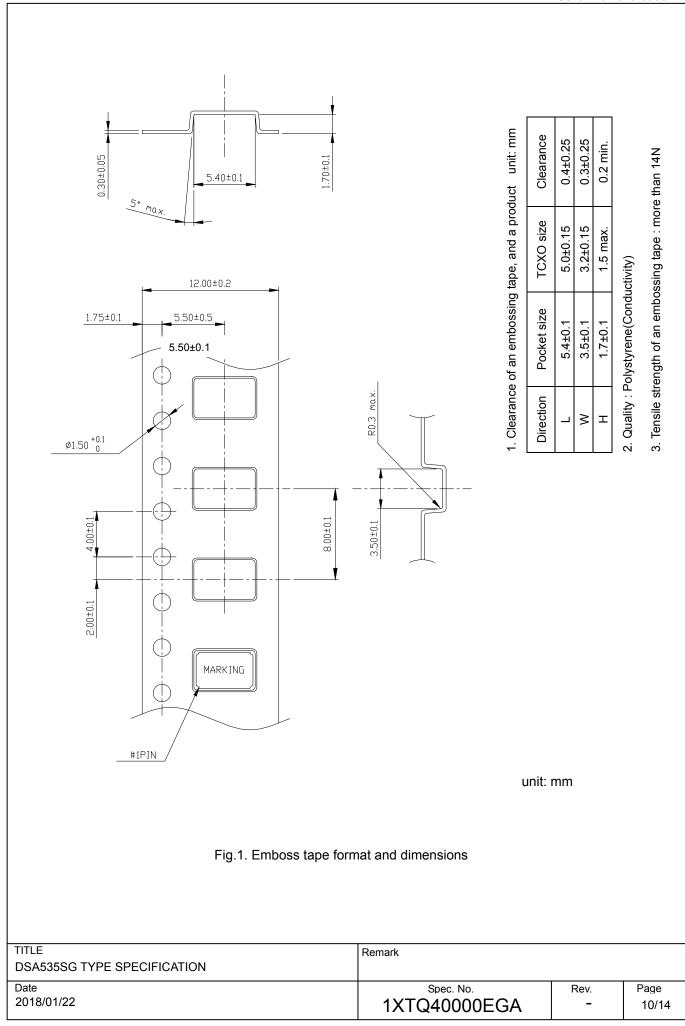


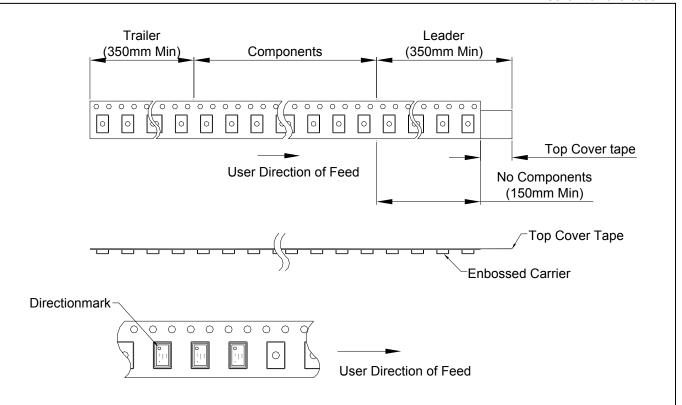


The product is packed up with the method which does not break in the handling by a shipping agent.

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DM-Z0002: Style-010 Ver.1





When a tape end is taken out to the front, sprocket holes becomes right hand side.

Peel strength

Pulling angle 165~180°, pulling speed at 300mm/min, strength should be 0.2~0.7N.

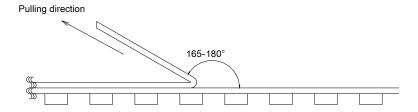
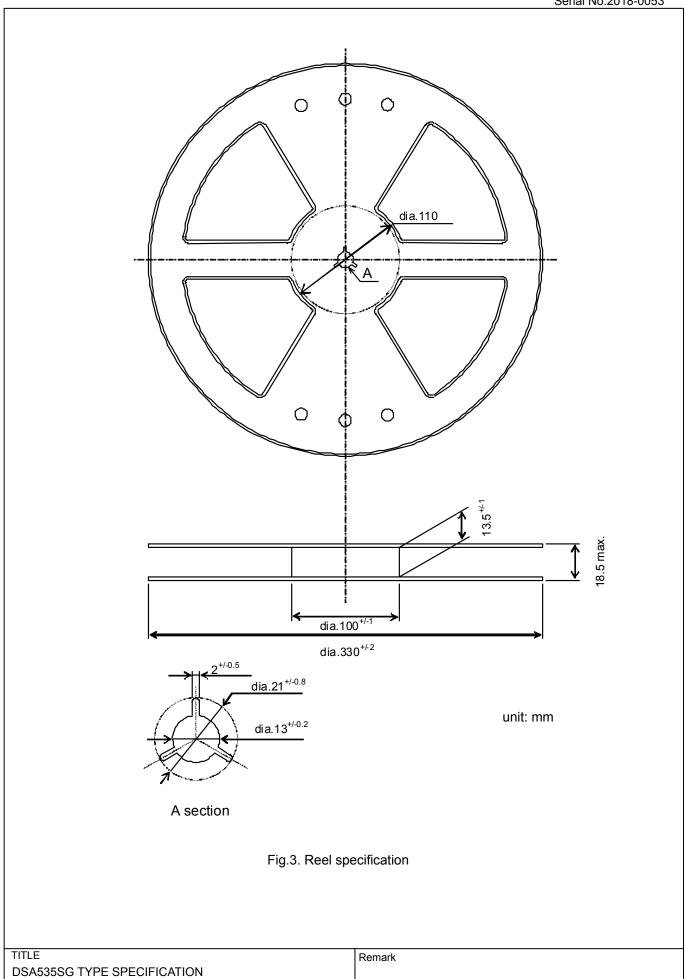


Fig.2. Taping specification

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16. Notes on mounting and handling

- 16.1 Storage environment
 - (1) The temperature and humidity of a storage place, Please give +5~+40°C and 40~85% as a standard.
 - (2) Please use this product within one year from the packing label date of issue.
 - (3) Please avoid the place which generates corrosive gas, and the place with much dirt.
 - (4) Please keep it in a place with little temperature change.

Dew condensation arises owing to a rapid temperature change and solderability becomes bad.

- 16.2 Be cautions to static electricity and high voltage.
- 16.3 This product has sufficient durability to fall and vibration. However, conditions may change to the fall after mounting to a PWB, and vibration. When you should drop on a floor the PWB which mounted the product or too much shock is added. Please use after a performance check.
- 16.4 Please check that the curvature of the substrate at the time of substrate cutting does not affect product. Moreover, especially when a product is near the position of a PWB guide pin, and the position of PWB break, be careful.
- 16.5 The part concerned does not correspond to washing.
- 16.6 Please repair at +260°C in 10s with hot air or +350°C in 5s with solder Iron.

17. Mandatory control

17.1 Ozone-depleting substance

It regulates by the U.S. air purifying method (November, 1990 establishment). ODS of CLASS1 and CLASS2 is not contained or used.

17.2 PBDE, PBBs

PBDE, PBBs are not contained into all the material currently used for this product.

17.3 RoHS

Following material restricted by RoHS (2011/65/EU) is not included or used. Lead, mercury, cadmium, hexavalent, chromium, PBB and PBDE.

17.4 Law Concerning Examination and Regulation of Manufacture, etc. of Chemical Substances

All the material currently used for this product is based on "Law Concerning Examination and Regulation of Manufacture, etc. of Chemical Substances". It is a registered material.

17.5 Lead

Leads, such as solder, are not used for this product. (Lead Free)

17.6 About the existence of silver and mercury use

The silver of very small quantity is contained in the conductive adhesives used for adhesion of Blank.

Moreover, mercury is used. It does not get down.

18. The country of origin / factory name / address

Country of origin: Japan

Factory name: DAISHINKU Corp. Tottori Production Div. Address: 7-3-21 Wakabadai minami, Tottori 689-1112

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2018-0053 REVERSION RECORD

Rev. No.	Date	Reason	Contents	Approved	Checked	Drawn
-	2018/01/22	-	Initial Release	H.Takase	S.Sakamoto	E.Kameda

DM-Z0002: Style-008 Ver.1